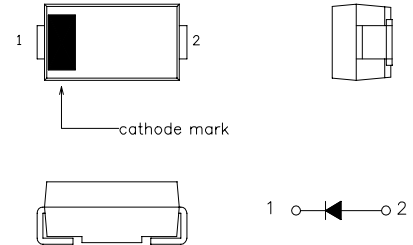


FRD Type : EC8FS6

FEATURES

- * Miniature Size, Surface Mount Device
- * Ultra-Fast Recovery
- * Low Forward Voltage Drop
- * Low Power Loss, High Efficiency
- * High Surge Capability
- * Packaged in 12mm Tape and Reel
- * Not Rolling During Assembly

OUTLINE DRAWING



Maximum Ratings

Approx Net Weight: 0.06g

Rating	Symbol	EC8FS6			Unit
Repetitive Peak Reverse Voltage	V _{RRM}	600			V
Average Rectified Output Current	I _O	0.65	Ta=25℃ *1	50Hz Half Sine Wave Resistive Load	A
		0.8	Ta=35℃ *2		
RMS Forward Current	I _{F(RMS)}	1.57			A
Surge Forward Current	I _{FSM}	20	50Hz Half Sine Wave,1cycle Non-repetitive		A
Operating JunctionTemperature Range	T _{jw}	-40 to +150			℃
Storage Temperature Range	T _{stg}	-40 to +150			℃

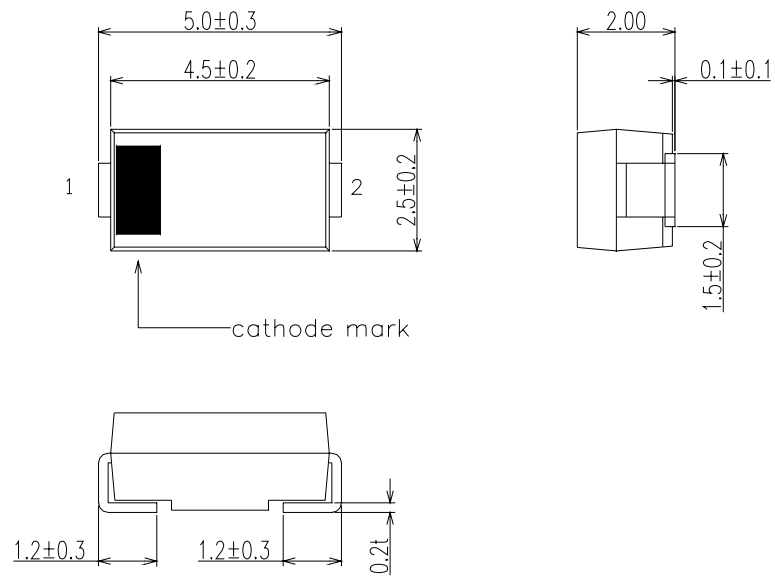
Electrical • Thermal Characteristics

Characteristics	Symbol	Conditions	Min.	Typ.	Max.	Unit	
Peak Reverse Current	I _{RM}	Tj= 25°C, V _{RM} = V _{RRM}	-	-	20	μA	
Peak Forward Voltage	V _{FM}	Tj= 25°C, I _{FM} = 0.8A	-	-	1.32	V	
Reverse Recovery Time	trr	I _{FM} = 1A, -di/dt= 50A/μs, Ta= 25°C	-	-	80	ns	
		I _F =I _R =10mA, Ta= 25°C			0.4	μs	
Thermal Resistance	Rth(j-a)	Junction to Ambient	*1	-	-	157	°C /W
			*2	-	-	108	

*1 Glass Epoxy Substrate Mounted (Soldering Lands=2x2mm, Both Sides)

*2 Alumina Substrate Mounted (Soldering Lands=2x2mm, Both Sides)

EC8FS6 OUTLINE DRAWING (Dimensions in mm)



SOLDERING PAD

